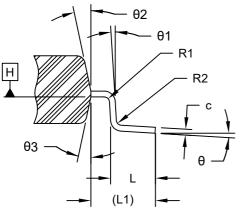
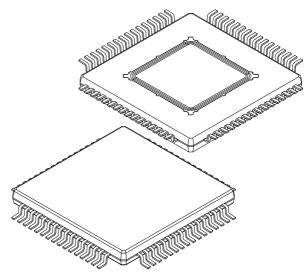
64-Lead Plastic Thin Quad Flat Pack (L8C) - 10x10x1.0 mm Body [TQFP] With 5.8 mm Grooved Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





SECTION A-A

	Units		MILLIMETERS		
Dimens	sion Limits	MIN	NOM	MAX	
Number of Terminals	N	64			
Pitch	е	0.50 BSC			
Overall Height	Α	-	-	1.20	
Standoff	A1	0.05	-	0.15	
Molded Package Thickness	A2	0.95	1.00	1.05	
Overall Length	D	12.00 BSC			
Molded Package Length	D1	10.00 BSC			
Exposed Pad Length	D2	5.80 REF			
Overall Width	E	12.00 BSC			
Molded Package Width	E1	10.00 BSC			
Exposed Pad Width	E2	5.80 REF			
Terminal Width	b	0.17	0.20	0.27	
Terminal Thickness	С	0.09	0.127	0.20	
Terminal Length	L	0.45	0.60	0.75	
Footprint	L1	1.00 REF			
Lead Bend Radius	R1	0.08	-	-	
Lead Bend Radius	R2	0.08	-	0.20	
Foot Angle	θ	0°	3.5°	7°	
Lead Angle	θ1	0°	-	-	
Mold Draft Angle	θ2	11°	12°	13°	
Mold Draft Angle	θ3	11°	12°	13°	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances. REF: Reference Dimension, usually without tolerance, for information purposes only.